

ASSIGNMENT OF APPLICATION

Docket Number : 01-099

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged,

We, the undersigned,

do hereby sell, assign, and transfer to:

LSI LOGIC CORPORATION, a corporation of Delaware, having a place of business at 1551 McCarthy Boulevard, Milpitas, California 95035, ("Assignee"), its successors, assigns, and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all inventions and improvements which are disclosed in the application for United States Letters Patent,

which has been executed by the undersigned concurrently herewith,

and which is entitled:

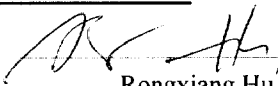
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in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application; and

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications to patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.


First named inventor

Name  Date: 08/15/97
Rongxiang Hu

Witness Signature:

Witness Printed Name:

Witness Address:


Connie del Castillo

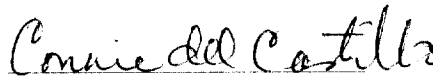
Second named inventor

Name  Date: 8/9/01
Philippe Schoenborn

Witness Signature:

Witness Printed Name:

Witness Address:


Connie del Castillo

LSI Logic Corporation
Intellectual Property
Corporate Legal Department
1551 McCarthy Blvd., MS D-106
Milpitas, California 95035

Third named inventor

Name

Masaichi Eda
Masaichi Eda

Date:

8/9/01

Witness Signature:

Connie del Castillo
Connie del Castillo

Witness Printed Name:

Witness Address:

LSI Logic Corporation
Intellectual Property
Corporate Legal Department
1551 McCarthy Blvd., MS D-106
Milpitas, California 95035